

August 2000

QFET™

FQD8P10 / FQU8P10

100V P-Channel MOSFET

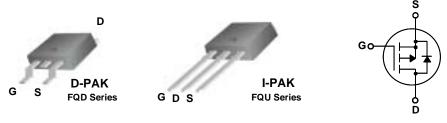
General Description

These P-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for low voltage applications such as audio amplifier, high efficiency switching DC/DC converters, and DC motor control.

Features

- -6.6A, -100V, $R_{DS(on)} = 0.53\Omega$ @ $V_{GS} = -10 \text{ V}$
- Low gate charge (typical 12 nC)
- Low Crss (typical 30 pF)
- Fast switching
- 100% avalanche tested
- · Improved dv/dt capability



Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter		FQD8P10 / FQU8P10	Units	
V _{DSS}	Drain-Source Voltage		-100	V	
I _D	Drain Current - Continuous (T _C = 25°C	C)	-6.6	Α	
	- Continuous (T _C = 100	°C)	-4.2	А	
I _{DM}	Drain Current - Pulsed	(Note 1)	-26.4	А	
V _{GSS}	Gate-Source Voltage		± 25	V	
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	150	mJ	
I _{AR}	Avalanche Current	(Note 1)	-6.6	А	
E _{AR}	Repetitive Avalanche Energy	(Note 1)	4.4	mJ	
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	-6.0	V/ns	
P_{D}	Power Dissipation (T _A = 25°C) *		2.5	W	
	Power Dissipation (T _C = 25°C)		44	W	
	- Derate above 25°C		0.35	W/°C	
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C	
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C	

Thermal Characteristics

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		2.84	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient *		50	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		110	°C/W

^{*} When mounted on the minimum pad size recommended (PCB Mount)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Cha	aracteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$	-100			V
ΔBV_{DSS} / ΔT_J	Breakdown Voltage Temperature Coefficient	I_D = -250 μA, Referenced to 2	5°C	-0.1		V/°C
I _{DSS}	Zana Cata Valtana Duain Courset	V _{DS} = -100 V, V _{GS} = 0 V			-1	μА
	Zero Gate Voltage Drain Current	V _{DS} = -80 V, T _C = 125°C			-10	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	$V_{GS} = -25 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = 25 V, V _{DS} = 0 V			100	nA
On Cha	racteristics		·			
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	-2.0		-4.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = -10 V, I _D = -3.3 A		0.41	0.53	Ω
9 _{FS}	Forward Transconductance	$V_{DS} = -40 \text{ V}, I_{D} = -3.3 \text{ A}$ (No	te 4)	4.1		S
C _{oss} C _{rss}	Output Capacitance Reverse Transfer Capacitance	$V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz		120 30	155 40	pF pF
orss	Neverse Hansier Capacitance			30	40	ρı
Switchi	ng Characteristics					
t _{d(on)}	Turn-On Delay Time	$V_{DD} = -50 \text{ V}, I_{D} = -8.0 \text{ A},$		11	30	ns
t _r	Turn-On Rise Time	$R_G = 25 \Omega$		110	230	ns
$t_{d(off)}$	Turn-Off Delay Time	S		20	50	ns
t _f	Turn-Off Fall Time	(Note	4, 5)	35	80	ns
Qg	Total Gate Charge	$V_{DS} = -80 \text{ V}, I_{D} = -8.0 \text{ A},$		12	15	nC
Q _{gs}	Gate-Source Charge	V _{GS} = -10 V		3.0		nC
Q _{gd}	Gate-Drain Charge	(Note	4, 5)	6.4		nC
Drain-S	Source Diode Characteristics a	nd Maximum Ratings				
I _S	Maximum Continuous Drain-Source Diode Forward Current				-6.6	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current				-26.4	Α
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = -6.6 A			-4.0	V
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V, } I_{S} = -8.0 \text{ A,}$		98		ns

- **Notes:**1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 5.2mH, I_{AS} = -6.6A, V_{DD} = -25V, R_G = 25 Ω, Starting T_J = 25°C 3. I_{SD} \leq -8.0A, di/dt \leq 300A/μs, V_{DD} \leq BV_{DSS}, Starting T_J = 25°C 4. Pulse Test : Pulse width \leq 300μs, Duty cycle \leq 2% 5. Essentially independent of operating temperature

Typical Characteristics

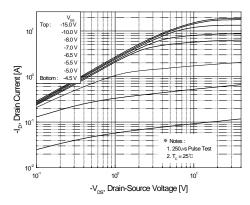


Figure 1. On-Region Characteristics

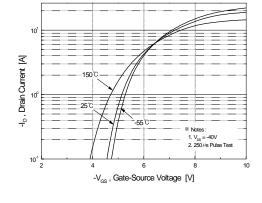


Figure 2. Transfer Characteristics

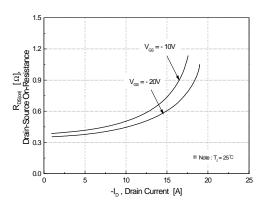


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

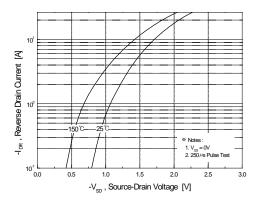


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

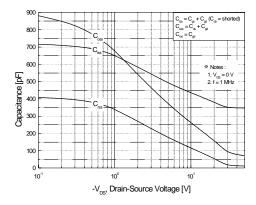


Figure 5. Capacitance Characteristics

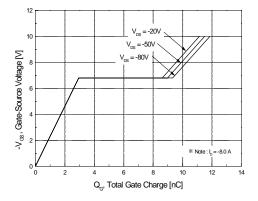
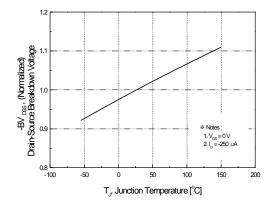


Figure 6. Gate Charge Characteristics

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Typical Characteristics (Continued)



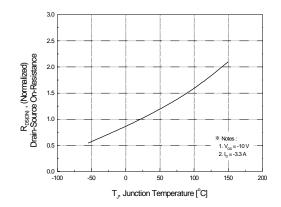
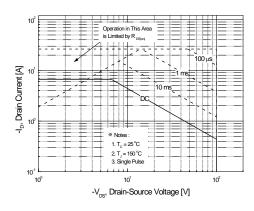


Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



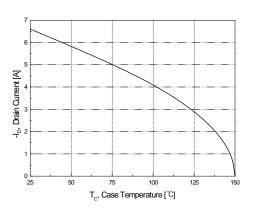


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

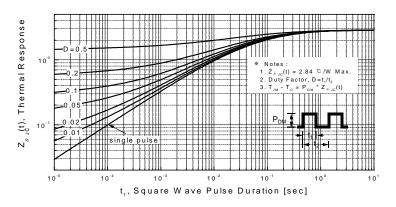
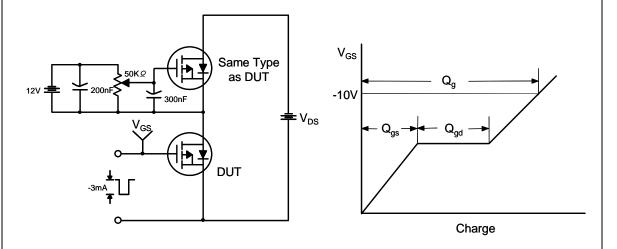


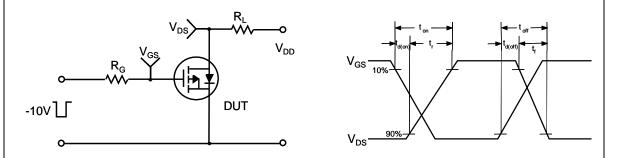
Figure 11. Transient Thermal Response Curve

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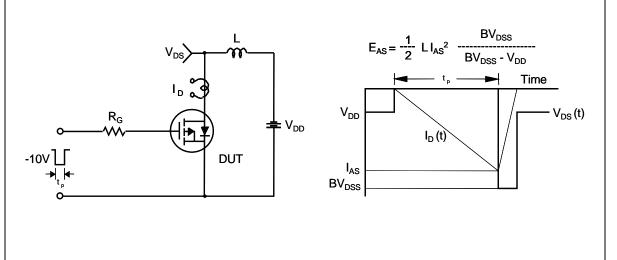
Gate Charge Test Circuit & Waveform



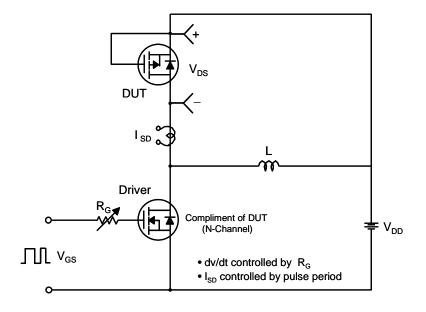
Resistive Switching Test Circuit & Waveforms

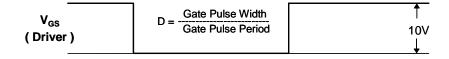


Unclamped Inductive Switching Test Circuit & Waveforms

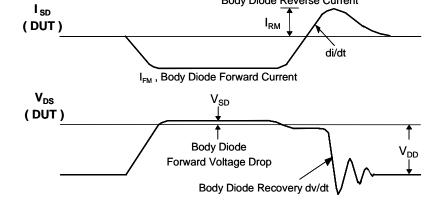


Peak Diode Recovery dv/dt Test Circuit & Waveforms

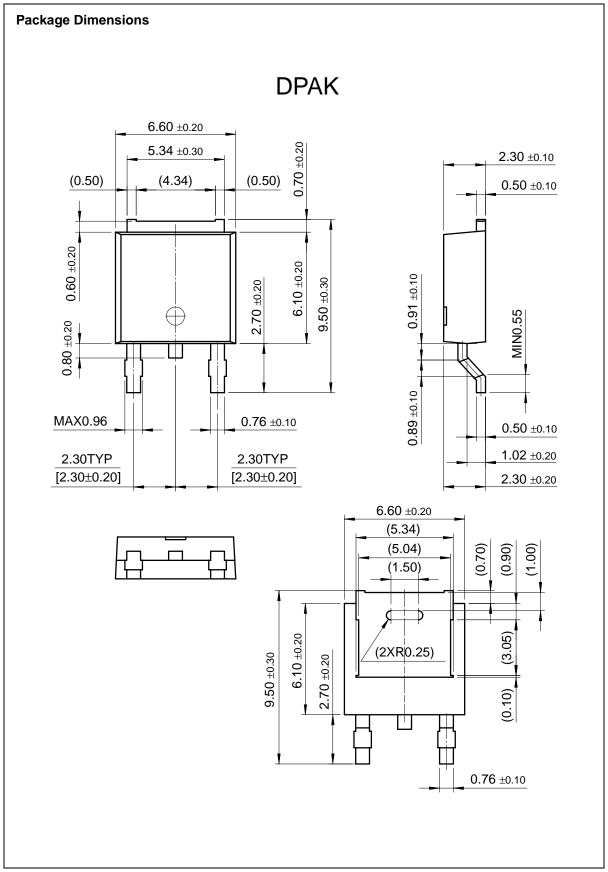




Body Diode Reverse Current

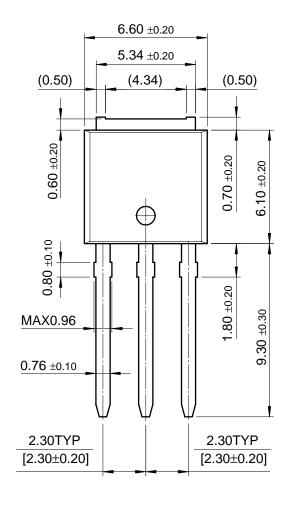


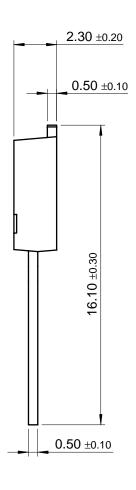
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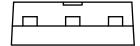




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